

Amendments to the Claims:

If entered, this listing of claims will replace all prior versions and listings of claims in the application.

Listing of Claims:

1. (Currently Amended) An integrated circuit device comprising:
an integrated circuit die fixably attached to a substrate and electrically connected to having a metal trace leads on said substrate;
an encapsulating layer overlying ~~encapsulating~~ said integrated circuit die
5 and substrate; and
an antenna structure of conductive loaded resin based material
comprising micron conductive fiber in a resin host overlying ~~molded onto~~ said encapsulating layer and ~~comprising a conductive loaded, resin based material~~
~~comprising conductive materials in a base resin host~~ and directly contacting said
10 metal trace leads through an opening in ~~are exposed by~~ said encapsulating layer and ~~said antenna structure~~.
2. (Currently Amended) The device according to Claim 1 wherein the ratio, by weight, of said micron conductive fiber ~~conductive materials~~ to said resin host is between about 0.20 and about 0.40.

3. (Currently Amended) The device according to Claim 1 ~~wherein said conductive materials comprise~~ further comprising metal powder.
4. (Original) The device according to Claim 3 wherein said metal powder is nickel, copper, or silver.
5. (Original) The device according to Claim 3 wherein said metal powder is a non-conductive material with a metal plating.
6. (Original) The device according to Claim 5 wherein said metal plating is nickel, copper, silver, or alloys thereof.
7. (Original) The device according to Claim 3 wherein said metal powder comprises a diameter of between about 3 μm and about 12 μm .
8. (Currently Amended) The device according to Claim 1 ~~wherein said conductive materials comprise~~ further comprising non-metal powder.
9. (Original) The device according to Claim 8 wherein said non-metal powder is carbon, graphite, or an amine-based material.

10. (Currently Amended) The device according to Claim 1 ~~wherein said~~
~~conductive materials comprise~~ further comprising a combination of metal powder
and non-metal powder.

11. (Canceled)

12. (Original) The device according to Claim 11 wherein said micron conductive
fiber is nickel plated carbon fiber, stainless steel fiber, copper fiber, silver fiber or
combinations thereof.

13. (Original) The device according to Claim 11 wherein said micron conductive
fiber has a diameter of between about 3 μm and about 12 μm and a length of
between about 2 mm and about 14 mm.

14. (Canceled)

15. (Canceled)

16. (Canceled)

17. (Canceled)

18. (Previously Presented) The device according to Claim 1 wherein said encapsulating layer comprises a resin-based material.

19. (Canceled)

20-72. (Canceled)